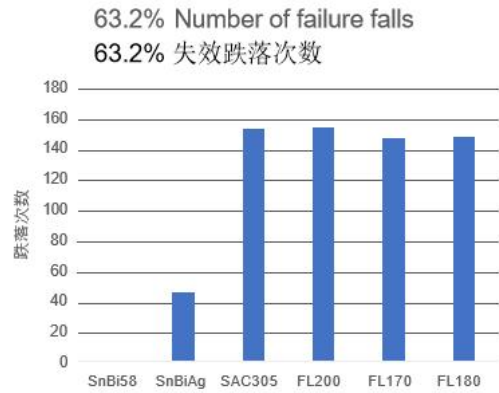
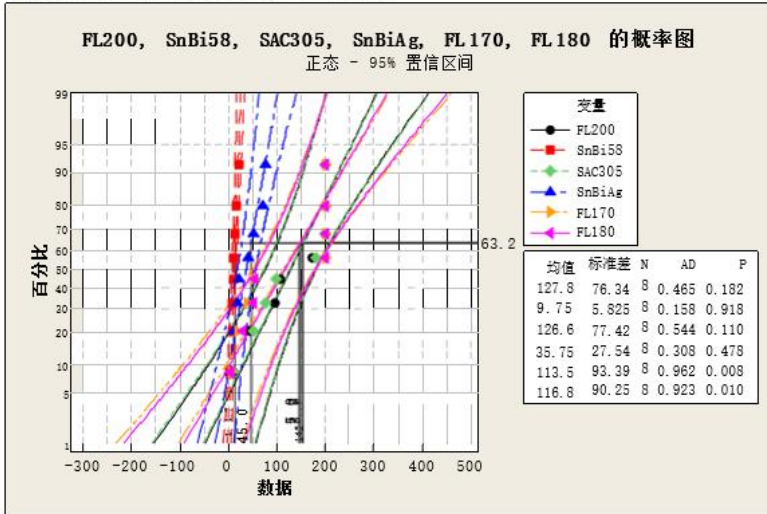




# Reliability Analysis

Sample: Amkor192CABGA (Daisychain),  
 Test conditions: 3000G acceleration (Altitude 700mm), Pulse width 0.2ms, Upto 200 falls,  
 Instantaneous cut-off condition: 100Ω, 0.1μ  
 样品: Amkor 192 CABGA (Daisy chain)  
 测试条件: 3000G加速度 (高度700mm),  
 脉宽0.2ms, 最多跌落200次, 瞬断条件: 100Ω, 0.1μ



170 低温焊料采用3000G加速度跌落测试, 其机械性能明显高于SnBi58、SnBiAg焊料, 与SAC305跌落性能相当。

170 low-temperature solder exhibits significantly superior mechanical properties to SnBi58 and SnBiAg solders when subjected to a 3000G acceleration drop test, demonstrating equivalent drop performance to SAC305.

## 低温焊料相关专利 Low-Temperature Solder-Related Patents

